

JAN 16 2004  
**OFFICIAL**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Patent Application Serial No. .... 09/784,234  
Filing Date ..... February 14, 2001  
Inventor ..... Shozo Nagano et al.  
Assignee ..... Honeywell International Inc.  
Group Art Unit ..... 1742  
Examiner ..... Ip, Sikyin  
Attorney Docket No. .... 30-5000-(4015)-DIV1  
Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating  
Anodes, Metal Alloys for Use as a Conductive Interconnection In an Integrated  
Circuit, and Physical Vapor Deposition Targets

**Mail Stop AFTER FINAL**  
**Commissioner for Patents**  
**P.O. Box 1450**  
**Alexandria, VA 22313-1450**

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Dated: January 16, 2004

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**RESPONSE TO NOVEMBER 18, 2003 FINAL OFFICE ACTION**

To: Mail Stop AFTER FINAL  
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**AMENDMENTS****Introductory Comments**

In reply to the Final Office Action dated November 18, 2003, applicant amends and  
remarks as follows.